

Minutes IEEE P802.3ch Multigig Automotive Ethernet PHY TF AdHoc meeting February 21, 2018

PRELIMINARY – 2/21/18 – PLEASE CHECK YOUR NAME IN THE ATTENDANCE!

Prepared by George Zimmerman

Proposed Agenda:

1. Agenda/Admin: George Zimmerman, agenda_3chah_01_020718.pdf
2. SG Chair's comments: no presentation (S. Carlson asked to give his comments at the end)
3. Presentations:
 - a. Natalie Wienckowski, GM North America – Potential Multi-Gig Ethernet Topologies
 - b. Natalie Wienckowski, GM North America – Chief Editor's Report
4. Discussion & Next steps – All

See [adhoc webpage for agenda deck and presentations](#)

Agenda/Admin George Zimmerman acting as ad hoc chair:

Meeting began at 7:06am PT.

Introductions & Affiliations.

Presented file: [agenda 3chah 01 022118.pdf](#)

1. Reviewed the Attendance information related to the ad hoc.
2. Displayed the Participation slide and reviewed it.
3. Displayed patent slide deck, and reviewed it.
Call for Patents was made at 7:13AM Pacific Time, none responded
4. Reminded participants to indicate full names and employer/affiliation for the meeting minutes.

Instructions for subscribing to the reflector may be found at <http://www.ieee802.org/3/ch/reflecter.html>. If you cannot subscribe to the reflector for some reason, and need additional assistance please contact the Task Force chair.

Presentations/Discussion:

Presentation: [Potential Multi-Gig Ethernet Topologies.](#), Natalie Wienckowski, GMNA

The presenter reviewed her view of potential multi-gigabit topologies, reflecting her experience in General Motors' plans for multi-gigabit. The discussion ranged to how other OEMs plans may differ, and the TF Chair reminded the group that the project has an objective for 15m and 4 connectors, which is the same reach and configurations found in the 100Mbps and 1000Mbps single-pair automotive ethernet.

For the presenter's topologies, a minimum segment length was 0.5 m, a maximum of 7m, and a total of 2 inline connectors. Other OEMs noted they might use down to 0.3m, but it would be unlikely to go shorter.

Discussion then moved to the link segment parameters adopted in Geneva, which brought up the Chief Editor's report.

Presentation: Chief Editor's Report – Natalie Wienckowski, Chief Editor, IEEE P802.3ch Task Force

The Chief Editor showed an early version of the draft, focusing on the adopted insertion loss and return loss baselines from Geneva. There was discussion around the return loss, which varied with insertion loss of the link. One participant urged those doing cabling modeling to look at the impact of short, possibly mismatched sections of a longer (high insertion loss) link segment to validate the baseline specifications.

Mr. Carlson, Chair of the Task Force added and clarified that while the group adopted baselines, baselines were just starting points. The actual levels and the frequency ranges are subject to change. The Chief Editor pointed to aspects of the specification she thought likely to change, in particular that the link segment definitions for the 2.5G and 5/10G were identical in both frequency range and values.

Feedback from PHY vendors and cable assembly vendors is encouraged to refine the baselines.

Chair's Comments & Discussion, Steve Carlson, Chair, IEEE P802.3ch Task Force:

Mr. Carlson reminded the group that requests for presentations were due the next day, and urged people to request on time. He discouraged sending many updates, correcting typos. He also encouraged joint presentations rather than 'supporters' lists, where there were actually multiple people involved in the work.

There was discussion of the timeline and the tasks for the march meeting agreed in Geneva, and participants were reminded to review the assigned tasks.

Closing Business

The next meeting will be at the March plenary, so please make use of the reflector.

Meeting closed –8:23am PT

Attendees (from Skype + emails)

Attendees without noted affiliations – please forward your affiliation for update

Names shown in **Gray Highlight** are usual attendees whose attendance we have not confirmed – PLEASE

First	Last	Affiliation
Sasha	Babenko	Molex
Alan	Barry	ADI
Devaraju	Basappa	
James	Bauer	Marvell
David	Brandt	Rockwell Automation
Steve	Carlson	High Speed Design/ Bosch
Mabud	Choudhury	OFS
Clark	Clarty	Cisco

Gerrit	den Besten	NXP
Eric	DiBiaso	TE Connectivity
Marc	Dupuis	Web Industries
Zhineng	Fan	Amphenol ICC
Matthias	Fritsche	Harting
Mike	Gardner	Molex
Rita	Horner	Synopsys
Yasuhiro	Hyakutake	Adamant Namiki Precision Jewel
Dalibor	Ignjatovic	ACOME
Venkat	Iyer	microchip
Matthias	Jaenecke	Yazaki
Chad	Jones	Cisco
Haysam	Kadry	Ford
Taiji	Kondo	Megachips
Larry	Matola	Aptiv
Brett	McClellan	Marvell
Thomas	Müller	Rosenberger
Waseem	Mir	Aptiv
Henry	Muyschondt	Microchip
Philipp	Numberger	MD Elektronik
Josef	Ohni	MD Elektronik
Doug	Oliver	Ford
Sujan	Pandey	NXP
Harsh	Patel	Molex
Damien	Quenson	Acome
Vilmalli	Raman	Yazaki Systems Technologies
Litsa	Rubino	Aptiv
Masood	Shariff	Commscope
Eric	Thompson	
Natalie	Wienckowski	GM
George	Zimmerman	CME Consulting/ADI, APL Group, Aquantia, BMW, Cisco, CommScope
Helge	Zinner	Continental
TOTAL	25 (confirmed)	Attendees